



12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN# 20251111000.2

**Adding TIEM-PR as additional wafer probe test site and
Qualify MLA as an additional Assembly/Test site for select devices
Change Notification / Sample Request**

Date: November 11, 2025

To: MOUSER PCN

Dear Customer:

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

Texas Instruments requires acknowledgement of receipt of this notification within 60 days of the date of this notice. Lack of acknowledgement of this notice within 60 days constitutes acceptance and approval of this change. If samples or additional data are required, requests must be received within 60 days of this notification.

The changes discussed within this PCN will not take effect any earlier than the proposed first ship date on Page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice or to provide acknowledgement of this PCN, you may contact your local Field Sales Representative or the change management team.

For sample requests or sample related questions, contact your local Field Sales Representative.

TI values customer engagement and feedback related to TI changes. Customers should contact TI if there are questions or concerns regarding a change notification.

Sincerely,

Change Management Team
SC Business Services

2025111000.2**Attachment: 1****Products Affected:**

The devices listed on this page are a subset of the complete list of affected devices. According to our records, you have recently purchased these devices. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
PCA9306TDCURQ1	PCA9306TDCURQ1
SN74LVC2T45QDCURQ1	SN74LVC2T45QDCURQ1
PCA9306IDCURQ1	PCA9306IDCURQ1
LSF0102QDCURQ1	LSF0102QDCURQ1
TCA39306DCURQ1	NULL

Technical details of this Product Change follow on the next page(s).

PCN Number:	20251111000.2	PCN Date:	November 11, 2025
Title:	Adding TIEM-PR as additional wafer probe test site and qualify MLA as an additional Assembly/Test site for select devices		
Customer Contact:	Change Management team	Dept:	Quality Services
Proposed 1st Ship Date:	May 10, 2026	Sample requests accepted until:	January 10, 2026*
*Sample requests received after January 10, 2026 will not be supported.			
Change Type:			
<input checked="" type="checkbox"/> Assembly Site	<input type="checkbox"/>	Design	<input type="checkbox"/> Wafer Bump Material
<input checked="" type="checkbox"/> Assembly Process	<input type="checkbox"/>	Data Sheet	<input type="checkbox"/> Wafer Bump Process
<input checked="" type="checkbox"/> Assembly Materials	<input type="checkbox"/>	Part number change	<input type="checkbox"/> Wafer Fab Site
<input type="checkbox"/> Mechanical Specification	<input checked="" type="checkbox"/>	Test Site	<input type="checkbox"/> Wafer Fab Material
<input checked="" type="checkbox"/> Packing/Shipping/ Labeling	<input type="checkbox"/>	Test Process	<input type="checkbox"/> Wafer Fab Process

PCN Details

Description of Change:

Texas Instruments is pleased to announce TIEM-PR as additional wafer probe test site for the devices listed below to support high volume ramps.

Group 1 Device - Wafer Probe Site

	Current	New
Probe Test Site	TI CDAT (CD-PR)	TI Melaka (TIEM-PR)

Test coverage, insertions, conditions will remain consistent with current testing.

Texas Instruments is pleased to announce the qualification of TI Malaysia (MLA) as an additional Assembly/Test site for the list of devices shown below. Material differences between sites are as follows.

Group 2 Device - Assembly Site

	Current Site	Additional Site
Assembly Site	HFTF	MLA
Mount Compound	SID#A-18 CRM-1076NS	4147858 QMI-505MT
Symbolization	Same	Additional
Final Wafer Thickness	152.4um	190um

Qual details are provided in the Qual Data Section.

Test coverage, insertions, conditions will remain consistent with current testing.

Reason for Change:

Continuity of supply.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

None.

Impact on Environmental Ratings

Checked boxes indicate the status of environmental ratings following implementation of this

change. If below boxes are checked, there are no changes to the associated environmental ratings.

RoHS	REACH	Green Status	IEC 62474
<input checked="" type="checkbox"/> No Change			

Changes to product identification resulting from this PCN:

Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City
HFTF	HFT	CHN	Hefei
TI Malaysia	MLA	MYS	Kuala Lumpur

Sample product shipping label (not actual product label)



Group 1 Product Affected:

LSF0102QDCURQ1	PCA9306TDCURQ1
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Group 2 Product Affected:

LSF0102QDCURQ1	PCA9306TDCURQ1	TCA39306DCURQ1
PCA9306IDCURQ1	SN74LVC2T45QDCURQ1	TCA9306TDCURHB

Qualification Report
Automotive Qualification Summary
(As per AEC-Q100 Rev. H and JEDEC Guidelines)
 Approve Date 02-October-2025

Product Attributes

Attributes		Qual Device: <u>PCA9306TDCURQ1</u>	Qual Device: <u>SN74LVC2T45QDCURQ1</u>	QBS Process Reference: <u>SN3257QDYYRQ1</u>	QBS Process Reference: <u>SN74HCS74QPWRQ1</u>
Automotive Grade Level		Grade 1		Grade 1	
Operating Temp Range (C)		-40 to 125		-40 to 125	
Product Function		Interface		Interface	
Wafer Fab Supplier		RFAB		RFAB	
Assembly Site		MLA		PHI	
Package Group		VSSOP		SOT	
Package Designator		DCU		DYY	
Pin Count		8		8	
				16	
				14	

QBS: Qual By Similarity, also known as Generic Data

Qual Device PCA9306TDCURQ1 is qualified at MSL1 260C

Qual Device SN74LVC2T45QDCURQ1 is qualified at MSL1 260C

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	#	Test Spec	Min Lot Qty	SS / Lot	Test Name	Condition	Duration	Qual Device: <u>PCA9306TDCURQ1</u>	Qual Device: <u>SN74LVC2T45QDCURQ1</u>	QBS Process Reference: <u>SN3257QDYYRQ1</u>	QBS Process Reference: <u>SN74HCS74QPWRQ1</u>
Test Group A - Accelerated Environment Stress Tests											
PC	A1	JEDEC J-STD-020 JESD22-A113	3	77	Preconditioning	MSL1 260C	-	-	3/0/0	3/0/0	3/0/0
HAST	A2	JEDEC JESD22-A110	3	77	Biased HAST	130C/85%RH	96 Hours	-	3/231/0	3/231/0	3/231/0
AC/UHAST	A3	JEDEC JESD22-A102/JEDEC JESD22-A118	3	77	Autoclave	121C/15psig	96 Hours	-	-	3/231/0	3/231/0
AC/UHAST	A3	JEDEC JESD22-A102/JEDEC JESD22-A118	3	77	Unbiased HAST	130C/85%RH	96 Hours	-	3/231/0	-	-
TC	A4	JEDEC JESD22-A104 and Appendix 3	3	77	Temperature Cycle	-65C/150C	500 Cycles	-	3/231/0	3/231/0	3/231/0
HTSL	A6	JEDEC JESD22-A103	1	45	High Temperature Storage Life	150C	1000 Hours	-	-	3/135/0	3/135/0
HTSL	A6	JEDEC JESD22-A103	1	45	High Temperature Storage Life	175C	500 Hours	-	3/135/0	-	-
Test Group B - Accelerated Lifetime Simulation Tests											
HTOL	B1	JEDEC JESD22-A108	3	77	Life Test	125C	1000 Hours	-	-	-	3/231/0
HTOL	B1	JEDEC JESD22-A108	3	77	Life Test	150C	300 Hours	-	-	3/231/0	-
ELFR	B2	AEC Q100-008	3	800	Early Life Failure Rate	125C	48 Hours	-	-	-	3/2400/0
ELFR	B2	AEC Q100-008	3	800	Early Life Failure Rate	150C	24 Hours	-	-	3/2400/0	-

Test Group C - Package Assembly Integrity Tests											
WBS	C1	AEC Q100-001	1	30	Wire Bond Shear	Minimum of 5 devices, 30 wires Cpk>1.67	Wires	1/30/0	1/30/0	3/90/0	3/90/0
WBP	C2	MIL-STD883 Method 2011	1	30	Wire Bond Pull	Minimum of 5 devices, 30 wires Cpk>1.67	Wires	1/30/0	1/30/0	3/90/0	3/90/0
SD	C3	JEDEC J-STD-002	1	15	PB Solderability	>95% Lead Coverage	-	-	-	1/15/0	1/15/0
SD	C3	JEDEC J-STD-002	1	15	PB-Free Solderability	>95% Lead Coverage	-	-	1/15/0	1/15/0	1/15/0
PD	C4	JEDEC JESD22-B100 and B108	3	10	Physical Dimensions	Cpk>1.67	-	1/10/0	1/10/0	3/30/0	3/30/0
Test Group D - Die Fabrication Reliability Tests											
EM	D1	JESD61	-	-	Electromigration	-	-	Completed Per Process Technology Requirements			
TDDB	D2	JESD035	-	-	Time Dependent Dielectric Breakdown	-	-	Completed Per Process Technology Requirements			
HCI	D3	JESD60 & 28	-	-	Hot Carrier Injection	-	-	Completed Per Process Technology Requirements			
BTI	D4	-	-	-	Bias Temperature Instability	-	-	Completed Per Process Technology Requirements			
SM	D5	-	-	-	Stress Migration	-	-	Completed Per Process Technology Requirements			
Test Group E - Electrical Verification Tests											
ESD	E2	AEC Q100-002	1	3	ESD HBM	-	2000 Volts	1/3/0	1/3/0	1/3/0	1/3/0
ESD	E3	AEC Q100-011	1	3	ESD CDM	-	1500 Volts	1/3/0	1/3/0	1/3/0	1/3/0
ESD	E3	AEC Q100-011	1	3	ESD CDM	-	500 Volts	1/3/0	1/3/0	-	1/3/0
LU	E4	AEC Q100-004	1	3	Latch-Up	Per AEC Q100-004	-	1/3/0	1/3/0	1/6/0	1/6/0
ED	E5	AEC Q100-009	3	30	Electrical Distributions	Cpk>1.67 Room, hot, and cold	-	3/90/0	3/90/0	3/90/0	3/90/0

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Grade 0 (or E): -40C to +150C

Grade 1 (or Q): -40C to +125C

Grade 2 (or T): -40C to +105C

Grade 3 (or I) : -40C to +85C

E1 (TEST): Electrical test temperatures of Qual samples (High temperature according to Grade level):

Room/Hot/Cold : HTOL, ED

Room/Hot : THB / HAST, TC / PTC, HTSL, ELFR, ESD & LU

Room : AC/uHAST

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

TI Qualification ID: R-CHG-2410-075

In performing change qualifications, Texas Instruments follows integrated circuit industry standards in performing defect mechanism analysis and failure mechanism-based accelerated environmental testing to ensure wafer fab process, assembly process and product quality and reliability. As encouraged by these standards, TI uses both product-specific and generic (family) data in qualifying its changes. For devices to be categorized as a 'product qualification family' for generic data purposes, they must share similar product, wafer fab process and assembly process elements. The applicability of generic data (also known at TI as Qualification

by Similarity (QBS)) is determined by the Reliability Engineering function following these industry standards. Generic data is shown in the qualification report in columns titled "QBS Process" (for wafer fab process), "QBS Package" (for assembly process) and "QBS Product" (for product family).

ZVEI ID: SEM-PA-18, SEM-PA-07, SEM-TF-01

For questions regarding this notice, e-mails can be sent to the Change Management team or your local Field Sales Representative.

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